

TOSHIBA Photocoupler GaAs IRED & Photo-Transistor

TLP781, TLP781F

- Office Equipment
- Household Appliances
- Solid State Relays
- Switching Power Supplies
- Various Controllers
- Signal Transmission Between Different Voltage Circuits

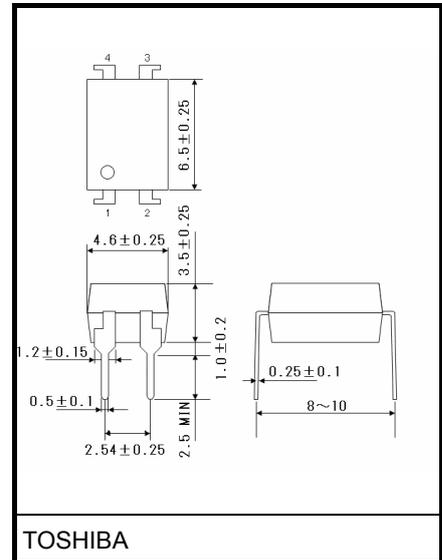
The TOSHIBA TLP781 consists of a silicone photo-transistor optically coupled to a gallium arsenide infrared emitting diode in a four lead plastic DIP (DIP4) with having high isolation voltage (AC: 5kVRMS (min)).

- TLP781 : 7.62mm pitch type DIP4
- TLP781F : 10.16mm pitch type DIP4
- Collector-emitter voltage: 80V (min.)
- Current transfer ratio: 50% (min.)
Rank GB: 100% (min.)
- Isolation voltage: 5000V_{rms} (min.)
- UL recognized: UL1577, file No. E67349
- BSI approved: BS EN60065:2002
Approved no.8961
BS EN60950-1:2006
Approved no.8962
- SEMKO approval: EN60950-1,EN60065 under plan
- Option(D4)type
VDE approved : DIN EN60747-5-2
Certificate No. 40021173
(Note): When an EN60747-5-2 approved type is needed,
Please designate "Option (D4)"

- Construction mechanical rating

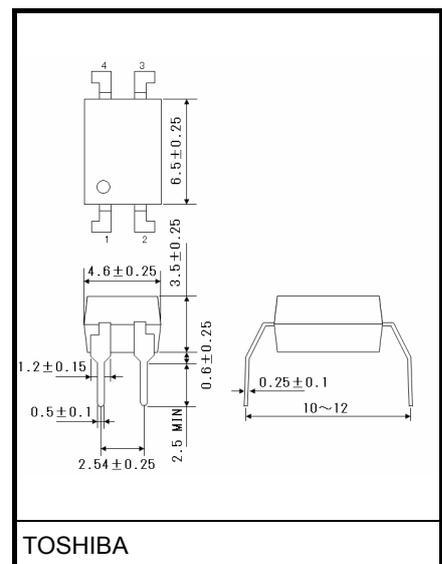
	7.62mm Pitch Standard Type	10.16mm Pitch TLPxxxF Type
Creepage distance	6.5mm(min)	8.0mm(min)
Clearance	6.5mm(min)	8.0mm(min)
Insulation thickness	0.4mm(min)	0.4mm(min)

TLP781 Unit in mm



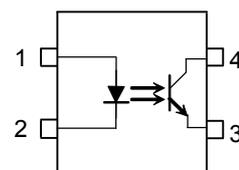
Weight: 0.25g (typ.)

TLP781F Unit in mm



Weight: 0.25g (typ.)

Pin Configurations (top view)



- 1 : Anode
- 2 : Cathode
- 3 : Emitter
- 4 : Collector

Current Transfer Ratio

Type	Classification (Note 1)	Current Transfer Ratio (%) (I_C / I_F)		Marking Of Classification
		$I_F = 5\text{mA}, V_{CE} = 5\text{V}, T_a = 25^\circ\text{C}$		
		Min	Max	
TLP781	(None)	50	600	Blank, Y, Y+, YE, G, G+, B, B+, BL, GB
	Rank Y	50	150	YE
	Rank GR	100	300	GR
	Rank BL	200	600	BL
	Rank GB	100	600	GB
	Rank YH	75	150	Y+
	Rank GRL	100	200	G
	Rank GRH	150	300	G+
	Rank BLL	200	400	B

(Note 1): Ex. rank GB: TLP781 (GB)

(Note 2): Application type name for certification test, please use standard product type name, i. e. TLP781 (GB): TLP781

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
LED	Forward current	I_F	60	mA
	Forward current derating ($T_a \geq 39^\circ\text{C}$)	$\Delta I_F / ^\circ\text{C}$	-0.7	mA / °C
	Pulse forward current (Note 3)	I_{FP}	1	A
	Power dissipation	P_D	100	mW
	Power dissipation derating	$\Delta P_D / ^\circ\text{C}$	-1.0	mW / °C
	Reverse voltage	V_R	5	V
	Junction temperature	T_j	125	°C
Detector	Collector-emitter voltage	V_{CEO}	80	V
	Emitter-collector voltage	V_{ECO}	7	V
	Collector current	I_C	50	mA
	Power dissipation (single circuit)	P_C	150	mW
	Power dissipation derating ($T_a \geq 25^\circ\text{C}$) (single circuit)	$\Delta P_C / ^\circ\text{C}$	-1.5	mW / °C
	Junction temperature	T_j	125	°C
Operating temperature range		T_{opr}	-55~110	°C
Storage temperature range		T_{stg}	-55~125	°C
Lead soldering temperature (10s)		T_{sol}	260	°C
Total package power dissipation		P_T	250	mW
Total package power dissipation derating ($T_a \geq 25^\circ\text{C}$)		$\Delta P_T / ^\circ\text{C}$	-2.5	mW / °C
Isolation voltage (Note 4)		BV_S	5000	V_{rms}

(Note): Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(Note 3): 100µs pulse, 100Hz frequency

(Note 4): AC, 1 min., R.H.≤ 60%. Apply voltage to LED pin and detector pin together.

Recommended Operating Conditions

Characteristic	Symbol	Min	Typ.	Max	Unit
Supply voltage	V _{CC}	—	5	24	V
Forward current	I _F	—	16	25	mA
Collector current	I _C	—	1	10	mA
Operating temperature	T _{opr}	-25	—	85	°C

(Note): Recommended operating conditions are given as a design guideline to obtain expected performance of the device.

Additionally, each item is an independent guideline respectively.

In developing designs using this product, please confirm specified characteristics shown in this document.

Individual Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
LED	Forward voltage	V _F	I _F = 10 mA	1.0	1.15	1.3	V
	Reverse current	I _R	V _R = 5 V	—	—	10	μA
	Capacitance	C _T	V = 0, f = 1 MHz	—	30	—	pF
Detector	Collector-emitter breakdown voltage	V _{(BR) CEO}	I _C = 0.5 mA	80	—	—	V
	Emitter-collector breakdown voltage	V _{(BR) ECO}	I _E = 0.1 mA	7	—	—	V
	Collector dark current	I _D (I _{CEO})	V _{CE} = 24 V	—	0.01	0.1	μA
			V _{CE} = 24 V Ta = 85°C	—	0.6	50	μA
Capacitance (collector to emitter)	C _{CCE}	V = 0, f = 1 MHz	—	10	—	pF	

Coupled Electrical Characteristics (Ta = 25°C)

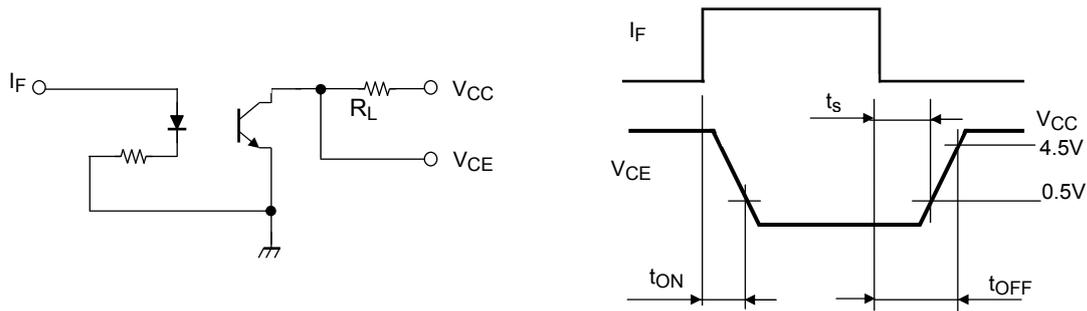
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Current transfer ratio	I _C / I _F	I _F = 5 mA, V _{CE} = 5 V Rank GB	50	—	600	%
			100	—	600	
Saturated CTR	I _C / I _F (sat)	I _F = 1 mA, V _{CE} = 0.4 V Rank GB	—	60	—	%
			30	—	—	
Collector-emitter saturation voltage	V _{CE} (sat)	I _C = 2.4 mA, I _F = 8 mA	—	—	0.4	V
		I _C = 0.2 mA, I _F = 1 mA Rank GB	—	0.2	—	
			—	—	0.4	

Isolation Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Capacitance (input to output)	C _S	V _S = 0, f = 1 MHz	—	0.8	—	pF
Isolation resistance	R _S	V _S = 500 V	1×10 ¹²	10 ¹⁴	—	Ω
Isolation voltage	BV _S	AC, 1 minute	5000	—	—	V _{rms}
		AC, 1 second, in oil	—	10000	—	
		DC, 1 minute, in oil	—	10000	—	V _{dc}

Switching Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Rise time	t_r	$V_{CC} = 10\text{ V}$, $I_C = 2\text{ mA}$ $R_L = 100\Omega$	—	2	—	μs
Fall time	t_f		—	3	—	
Turn-on time	t_{on}		—	3	—	
Turn-off time	t_{off}		—	3	—	
Turn-on time	t_{ON}	$R_L = 1.9\text{ k}\Omega$ (Note 5) $V_{CC} = 5\text{ V}$, $I_F = 16\text{ mA}$	—	2	—	μs
Storage time	t_s		—	25	—	
Turn-off time	t_{OFF}		—	50	—	

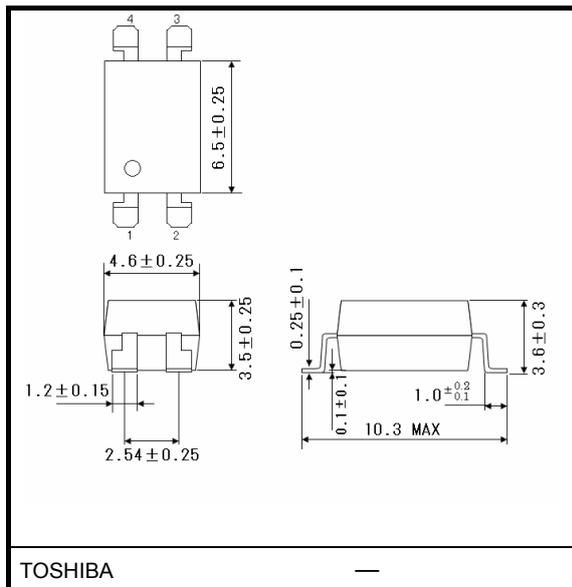


(Note 5): Switching time test circuit

Surface-Mount Lead Form Options

TLP781(LF6)

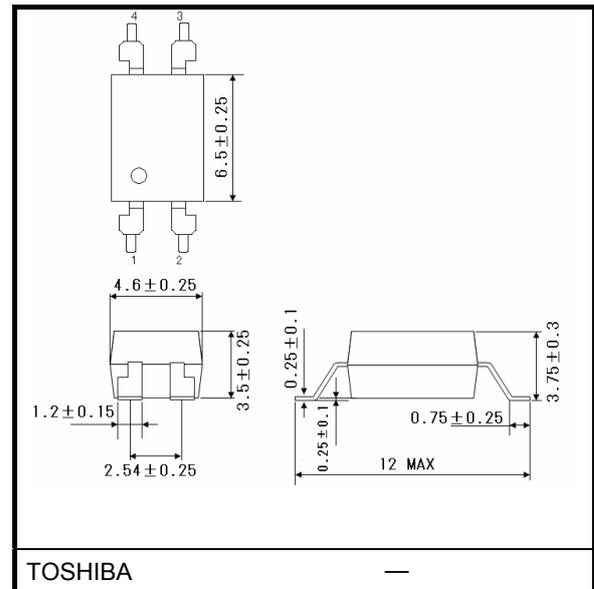
Unit in mm



Weight : 0.24g (typ.)

TLP781F(LF7)

Unit in mm



Weight : 0.24g (typ.)

Specifications for Embossed-Tape Packing: (TP6), (TP7)

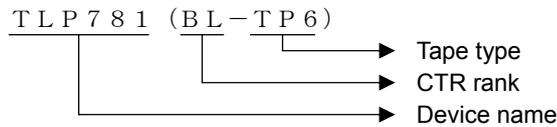
1. Applicable Package

Package Name	Product Type
DIP4LF6	TLP781
DIP4LF7	TLP781F

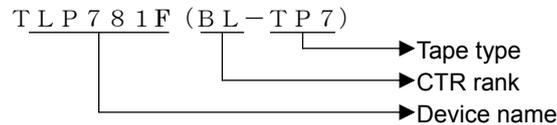
2. Product Naming System

Type of package used for shipment is denoted by a symbol suffix after a product number. The method of classification is as below.

(Example 1)



(Example 2)



3. Tape Dimensions

3.1 Orientation of Device in Relation to Direction of Tape Movement

Device orientation in the recesses is as shown in Figure 1.

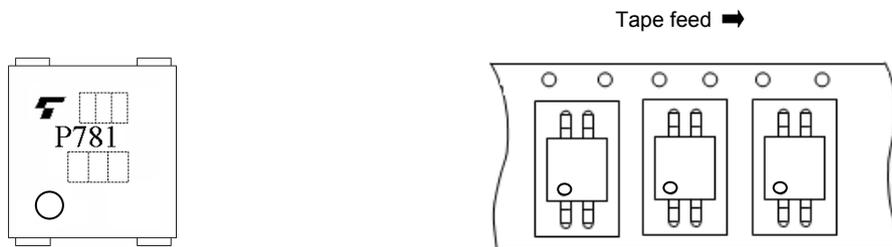


Figure1 Device Orientation

3.2 Tape Packing Quantity:2000 devices per reel

3.3 Empty Device Recesses Are as Shown in Table 1.

Table1 Empty Device Recesses

	Standard	Remarks
Occurrences of 2 or more successive empty device recesses	0	Within any given 40-mm section of tape, not including leader and trailer
Single empty device recesses	6 devices (max.) per reel	Not including leader and trailer

3.4 Start and End of Tape

The start of the tape has 30 or more empty holes. The end of the tape has 50 or more empty holes.

3.5 Tape Specification

[1] TLP781 (TP6)

- (1)Tape material: Plastic
- (2)Dimensions: The tape dimensions are as shown in Figure 2.

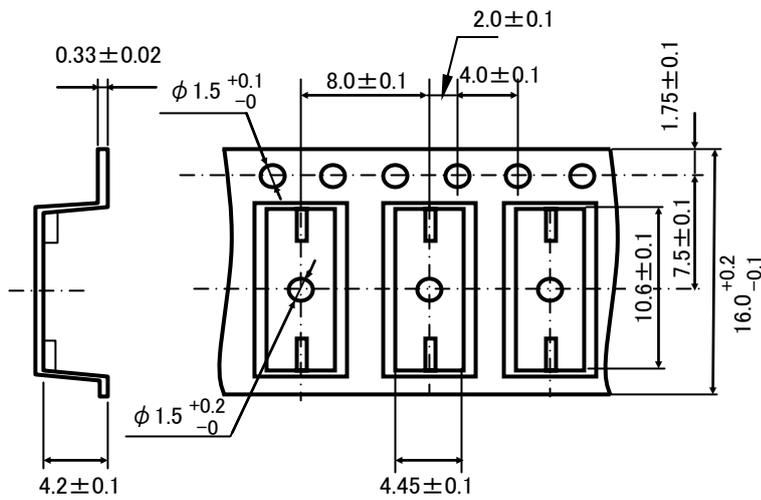


Figure 2 Tape Forms

[2] TLP781F (TP7)

- (1)Tape material: Plastic
- (2)Dimensions: The tape dimensions are as shown in Figure 3.

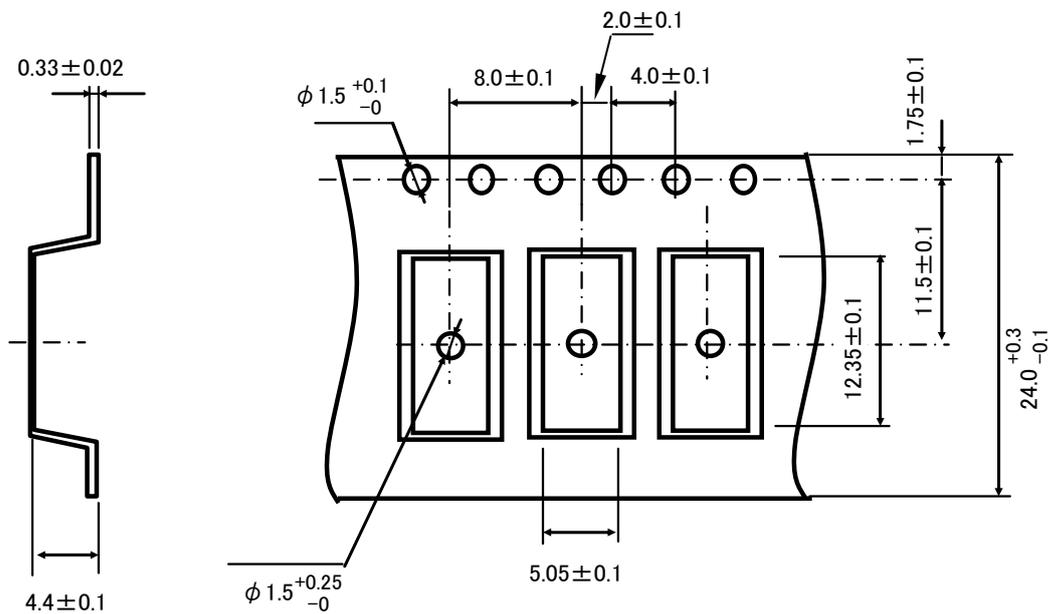


Figure 3 Tape Forms

3.6 Reel Specification

[1] TLP781 (TP6)

(1)Material: Plastic

(2)Dimensions: The reel dimensions are as shown in Figure 4.

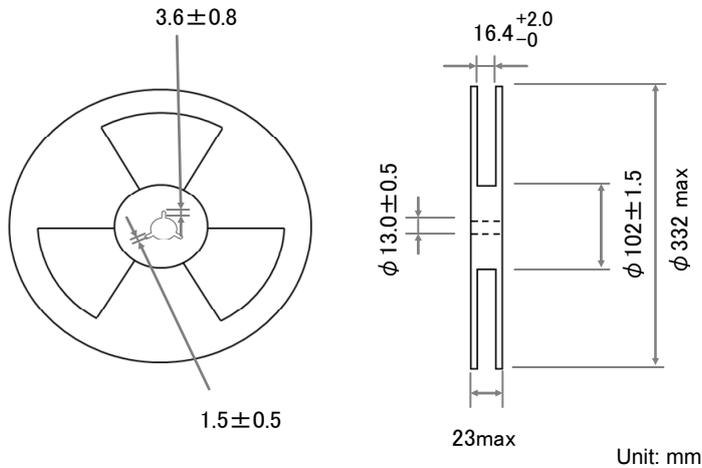


Figure 4 Reel Forms

[2] TLP781F (TP7)

(1)Material: Plastic

(2)Dimensions: The reel dimensions are as shown in Figure 5.

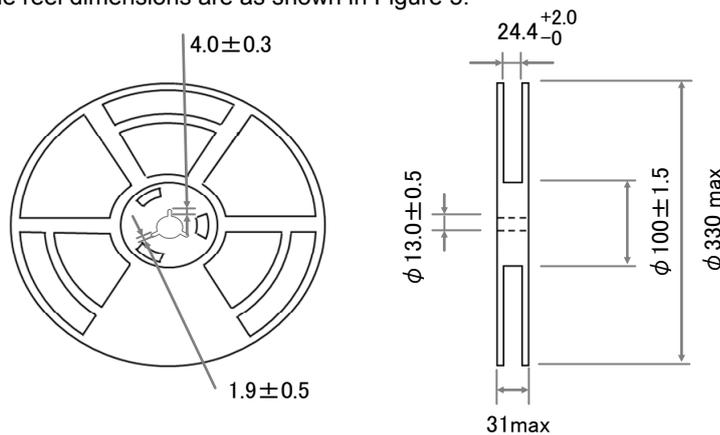


Figure 5 Reel Forms

4. Packing

One reel of photocouplers is packed in a shipping carton.

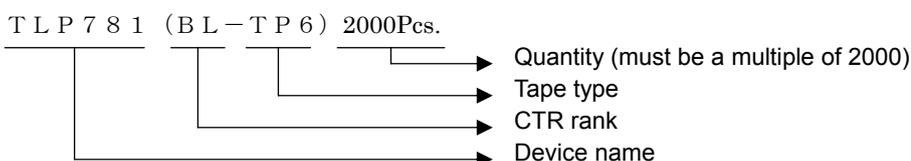
5. Label Indication

The carton bears a label indicating the product number, the symbol representing classification of standard, the quantity, the lot number and the Toshiba company name.

6. Ordering Information

When placing an order, please specify the product number, the CTR rank, the tape type and the quantity as shown in the following example.

(Example)



(Note): The order code may be suffixed with wither a letter or a digit.

Please contact your nearest Toshiba sales representative for more details.

Soldering and Storage

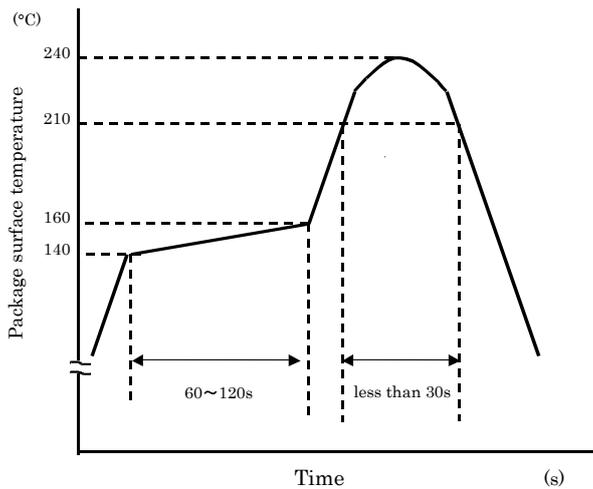
1. Soldering

1.1 Soldering

When using a soldering iron or medium infrared ray/hot air reflow, avoid a rise in device temperature as much as possible by observing the following conditions.

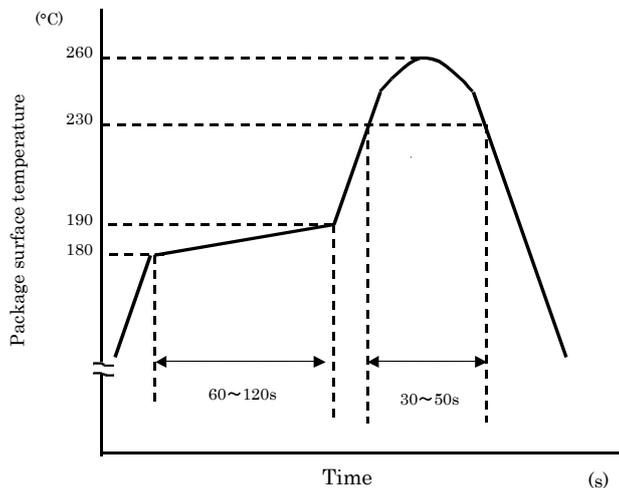
1) Using solder reflow

·Temperature profile example of lead (Pb) solder



This profile is based on the device's maximum heat resistance guaranteed value. Set the preheat temperature/heating temperature to the optimum temperature corresponding to the solder paste type used by the customer within the described profile.

·Temperature profile example of using lead (Pb)-free solder



This profile is based on the device's maximum heat resistance guaranteed value. Set the preheat temperature/heating temperature to the optimum temperature corresponding to the solder paste type used by the customer within the described profile.

2) Using solder flow (for lead (Pb) solder, or lead (Pb)-free solder)

- Please preheat it at 150°C between 60 and 120 seconds.
- Complete soldering within 10 seconds below 260°C. Each pin may be heated at most once.

3) Using a soldering iron

Complete soldering within 10 seconds below 260°C, or within 3 seconds at 350°C. Each pin may be heated at most once.

2. Storage

- 1) Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- 2) Follow the precautions printed on the packing label of the device for transportation and storage.
- 3) Keep the storage location temperature and humidity within a range of 5°C to 35°C and 45% to 75%, respectively.
- 4) Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- 5) Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- 6) When restoring devices after removal from their packing, use anti-static containers.
- 7) Do not allow loads to be applied directly to devices while they are in storage.
- 8) If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

EN60747 Isolation Characteristics

Types: TLP781, TLP781F

Type designations for 'option: (D4) ', which are tested under EN60747 requirements.

Ex.: TLP781 (D4-GR-LF6) D4: EN60747 option
 GR: CTR rank name
 LF6: standard lead bend name

Note: Use TOSHIBA standard type number for safety standard application.

Ex. TLP781 (D4-GR-LF6) → TLP781

Description	Symbol	Rating	Unit
Application classification for rated mains voltage $\leq 300 V_{rms}$ for rated mains voltage $\leq 600 V_{rms}$		I-IV I-III	—
Climatic classification		55 / 115 / 21	—
Pollution degree		2	—
Maximum operating insulation voltage	V_{IORM}	890	Vpk
Input to output test voltage, $V_{pr} = 1.5 \times V_{IORM}$, type and sample test $t_p = 10s$, partial discharge $< 5pC$	V_{pr}	1335	Vpk
Input to output test voltage, $V_{pr} = 1.875 \times V_{IORM}$, 100% production test $t_p = 1s$, partial discharge $< 5pC$	V_{pr}	1670	Vpk
Highest permissible overvoltage (transient overvoltage, $t_{pr} = 60s$)	V_{TR}	6000	Vpk
Safety limiting values (max. permissible ratings in case of fault) current (input current I_F , $P_{Si} = 0$) power (output or total power dissipation) temperature	I_{Si} P_{Si} T_{Si}	300 500 150	mA mW °C
Insulation resistance, $V_{IO} = 500V, T_a = 25^\circ C$	R_{Si}	$\geq 10^{12}$	Ω

Insulation Related Specifications

		 7.62mm pitch TLPxxx type	 10.16mm pitch TLPxxxF type
Minimum creepage distance	Cr	6.5mm	8.0mm
Minimum clearance	Cl	6.5mm	8.0mm
Minimum insulation thickness	ti	0.4 mm	
Comparative tracking index	CTI	175	

- (1) If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value. (e.g. at a standard distance between soldering eye centres of 7.5mm). If this is not permissible, the user shall take suitable measures.
- (2) This photocoupler is suitable for 'safe electrical isolation' only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.

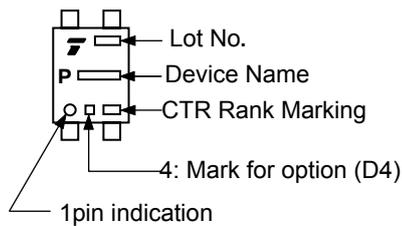
VDE test sign: Marking on product
for EN60747

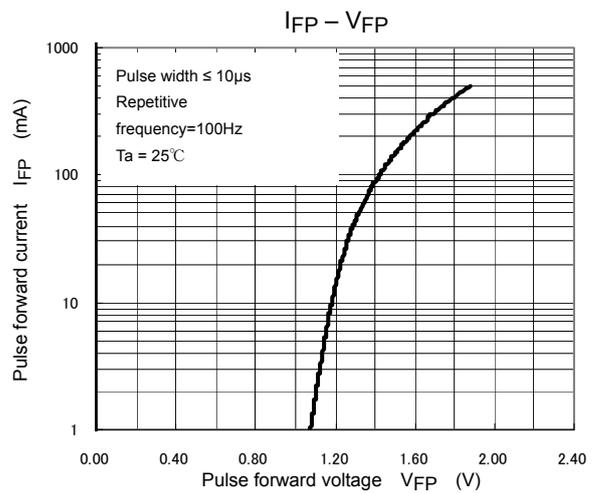
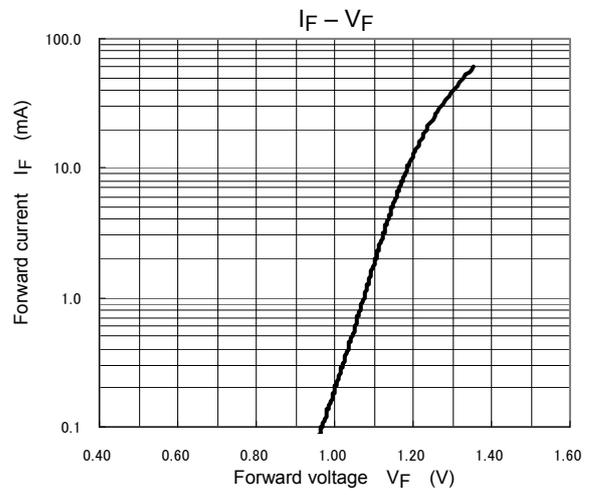
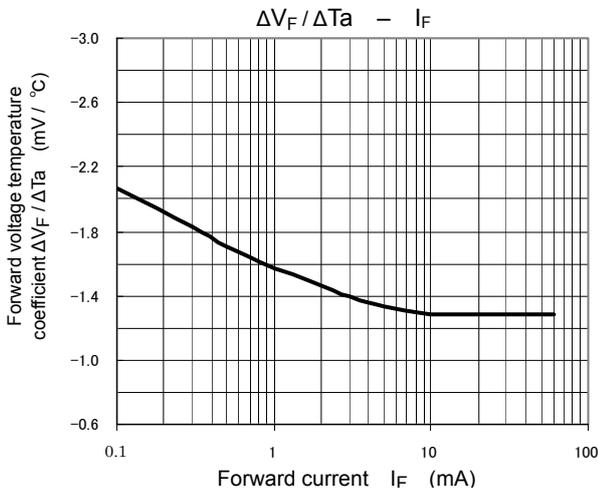
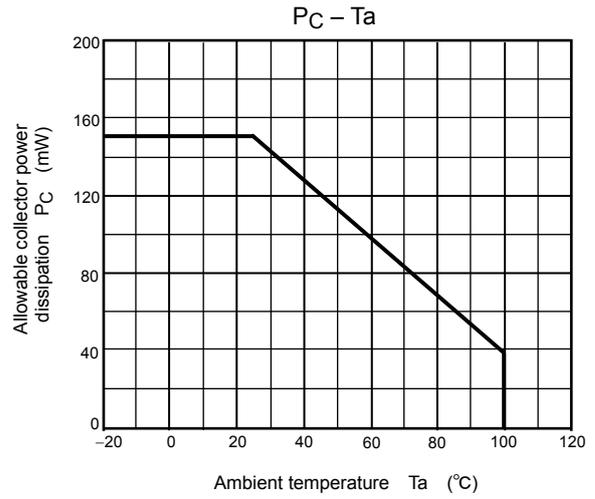
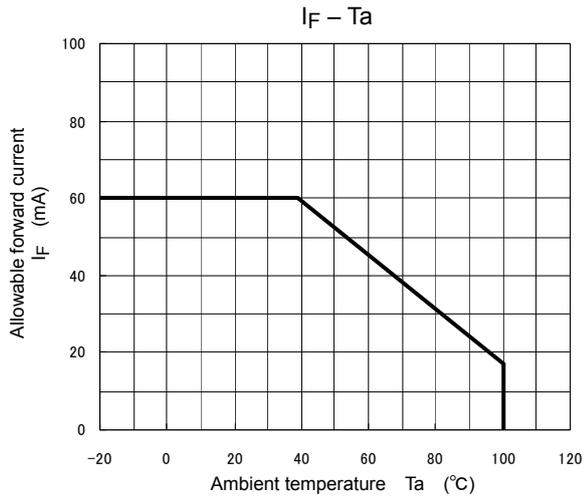
4

Marking on packing
for EN60747

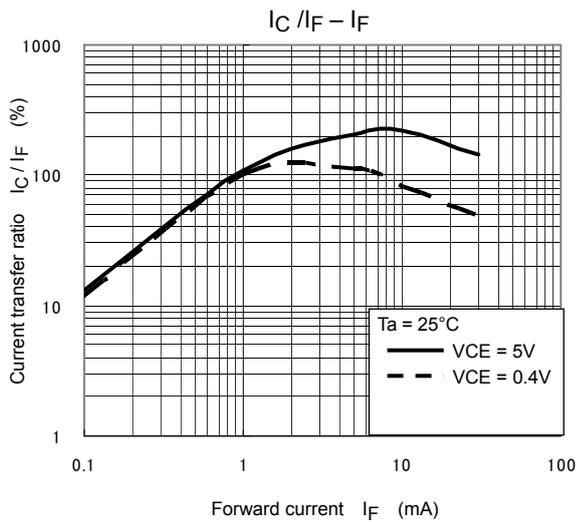
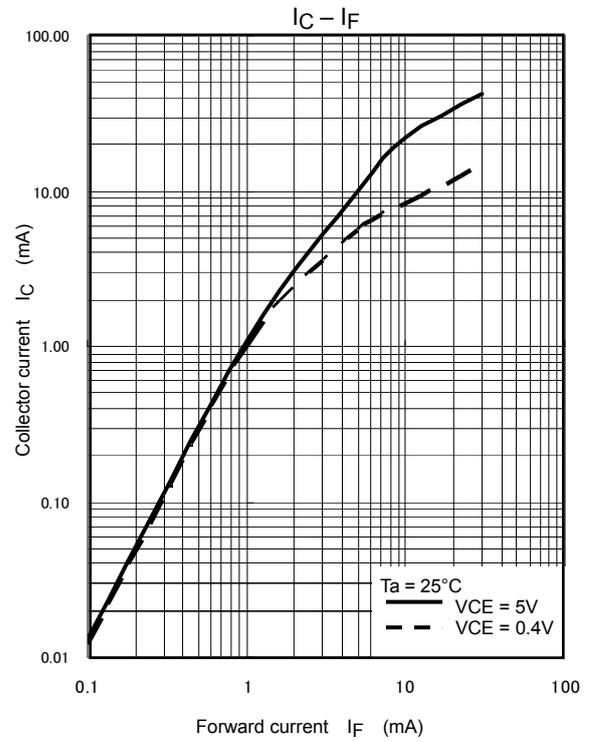
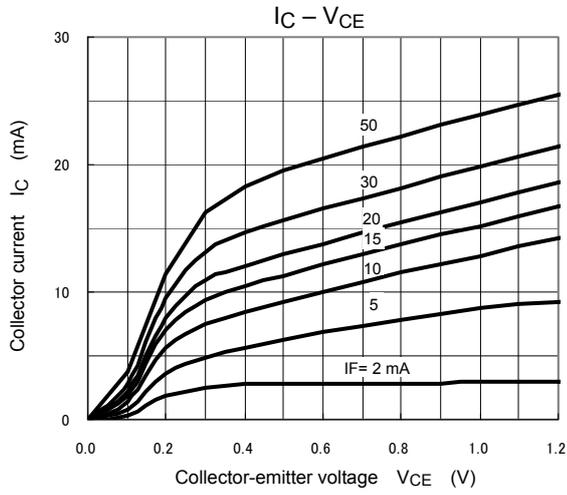
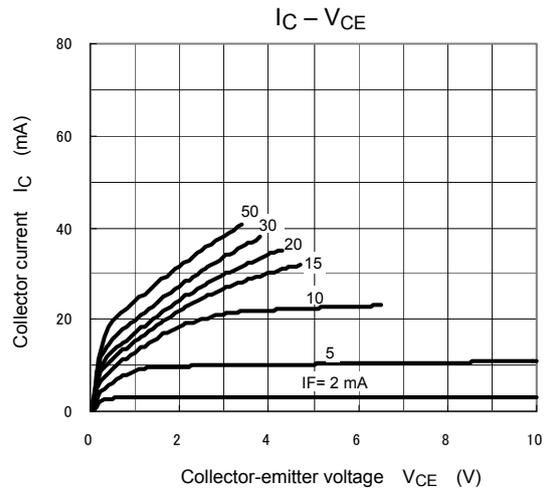
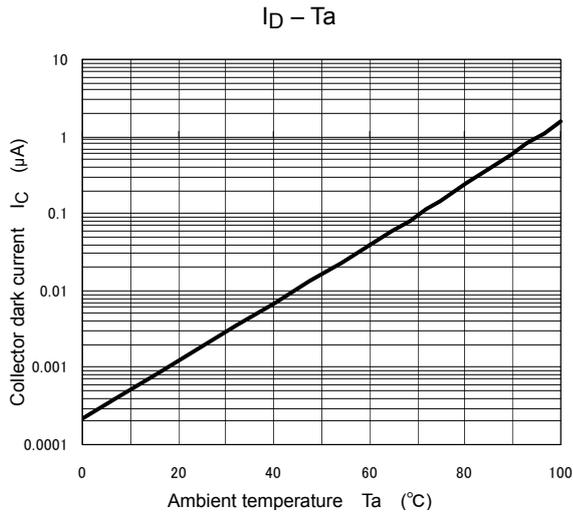


Marking Example: TLP781, TLP781F

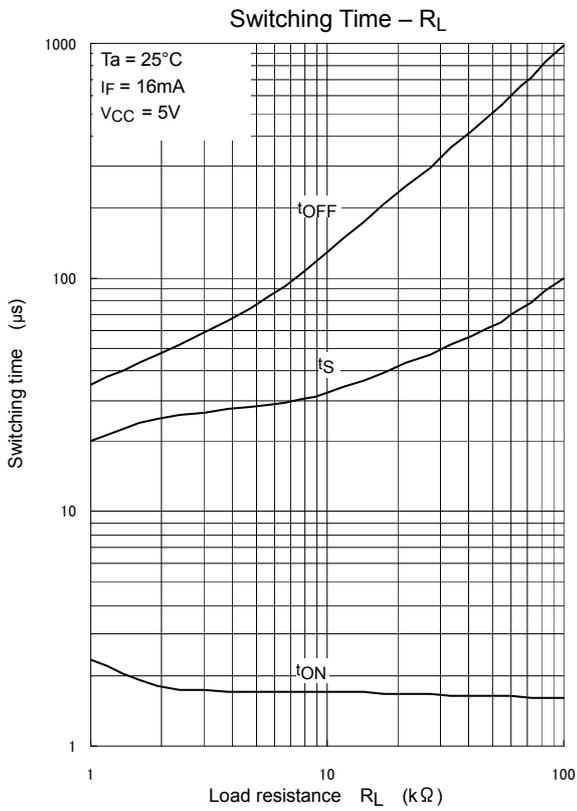
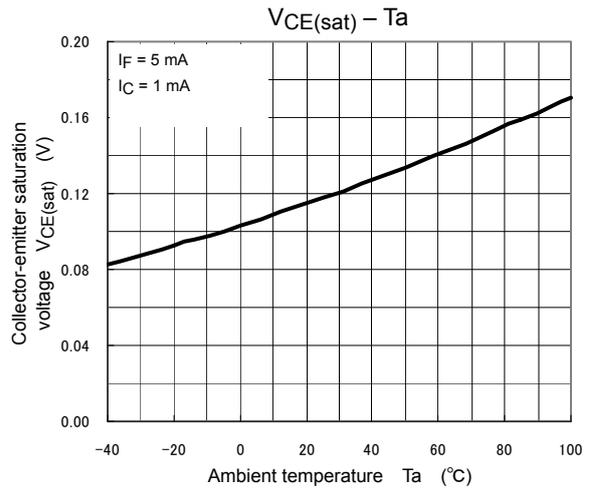
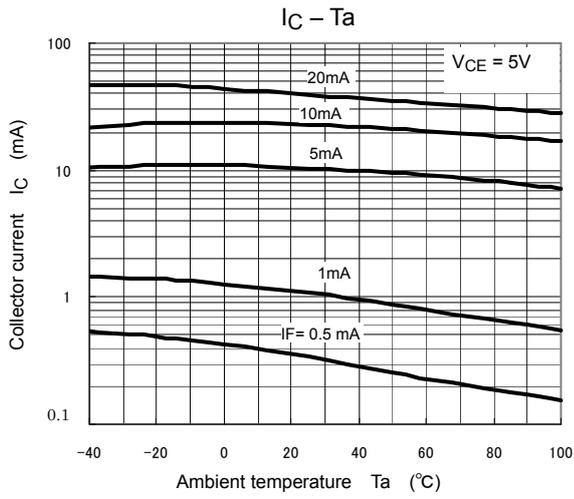




*: The above graphs show typical characteristics.



*: The above graphs show typical characteristics.



*: The above graphs show typical characteristics.

RESTRICTIONS ON PRODUCT USE

20070701-EN

- The information contained herein is subject to change without notice.
- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc.
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- The products described in this document shall not be used or embedded to any downstream products of which manufacture, use and/or sale are prohibited under any applicable laws and regulations.
- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patents or other rights of TOSHIBA or the third parties.
- GaAs(Gallium Arsenide) is used in this product. The dust or vapor is harmful to the human body. Do not break, cut, crush or dissolve chemically.
- Please contact your sales representative for product-by-product details in this document regarding RoHS compatibility. Please use these products in this document in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances. Toshiba assumes no liability for damage or losses occurring as a result of noncompliance with applicable laws and regulations.